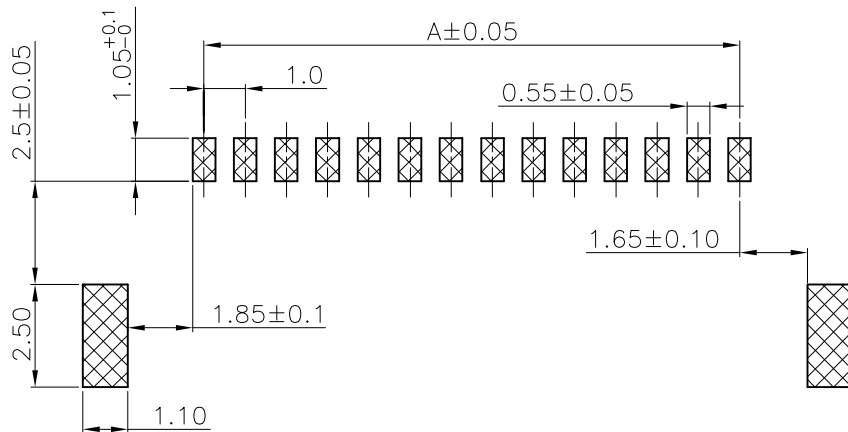
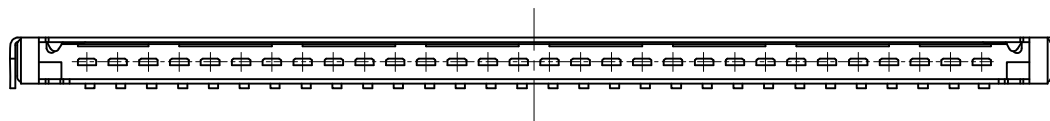
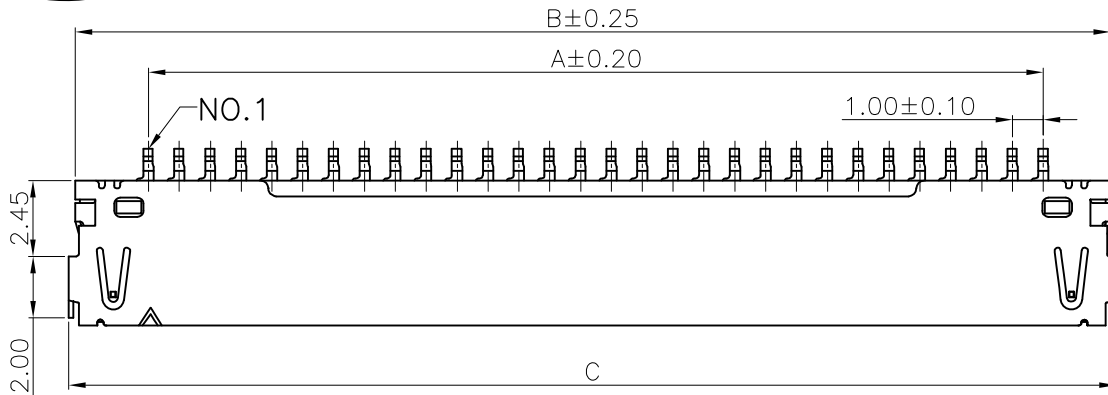


The product using material and processing must conform to the "WL-PZ-001"HSF technical standard control requirements

RoHS+HF



Recommended PCB LAYOUT

NOTE:

- 1.MATERIAL SPECIFICATION:
1-1.HOUSING: LCP,UL94V-0
1-2.CONTACTS: PHOSPHOR BRONZE
1-3.SHELL: PHOSPHOR BRONZE
2.PLATING SPECIFICATION:
2-1.CONTACTS:
TIN/GOLD FLASH PLATED OVER ALL.
2-2.SHELL:
MATTE TIN PLATED OVER ALL.
3.MECHANICAL PERFORMANCE:
3-1.RETENTIVITY FORCE: 0.1KGF/pin min
3-2.DURABILITY: 50 CYCLES.
4.ELECTRICAL PERFORMANCE:
4-1.CURRENT RATING: 1.0A AV,DC
RATED VOLTAGE : 100V AV,DC
4-2.CONTACT RESISTANCE: 30mΩ MAX
4-3.INSULATION RESISTANCE: 500MΩ Min
4-4.DIELECTRIC WITHSTANDING : 500V
5.ENVIRONMENTAL PERFORMANCE:
5-1.OPERATING TEMPERATURE: -25°C~+85°C.
6.PACKAGE SPEC: RELL
7.P/N:
- A1** A1004 W 9-1 XX 2 X X 0
SERIES NO: W 9-1 XX 2 X X 0
CONNECTOR: W-WAFER
ANGLE: 9-90°
0-180°
ROW NO: 1-SINGLE ROW
PIN Q'PY: 14~30 Pin
COLOR: A-BLACK
S-NATURE
PLATING: A-ALL AU G/F
C-BRIGHT TIN
D-MATTE TIN
TERMIPOINT: 2-SMT

Circuit	A	B	C
14	13.00	17.55	17.95
20	19.00	23.55	23.95
30	29.00	33.55	33.95